ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20099

Generic Copy

Issue Date: 30-May-2013

TITLE: Addition of manufacturing facility (ASECL) of Test and Assembling process for LC898111AXB-MH

PROPOSED FIRST SHIP DATE: 01-Oct-2013

AFFECTED CHANGE CATEGORY(S): Test & Assembly site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Ikuo.Saeki@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is to notify customers of Test, Dicing and Taping site addition of LC898111AXB.
In order to increase mass production capacity, the addition plan of manufacturing line (Test, Dicing and Taping) in ASECL (Chung-Li) for LC898111AXB will be started.

As for this change, there is no influence on product

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QUALIFICATION PLAN:

Reliability Test Conditions
・MSL 1 Preconditioning (PC) 3xIR @ 260 ºC
・Preconditioning +Temp Cycling (PC+TC)_Temp=-65ºC to +150ºC for 200 cycles
・Preconditioning +Autoclave (PC+AC)_Temp= +121ºC;RH=100% 15 PSIG for 96 hours
・Preconditioning +High humidity/temperature(PC+THS)_Temp=+85ºC;RH=85% for 504 hours
・Scanning Acoustic Tomography (SAT)

List of affected General Parts:

LC898111AXB-MH